



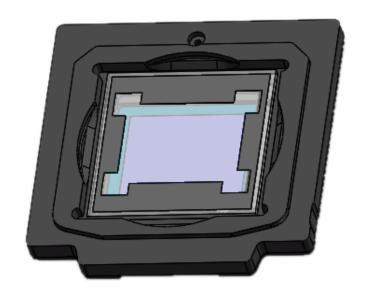
Introduction of COM

- Chip On Module -

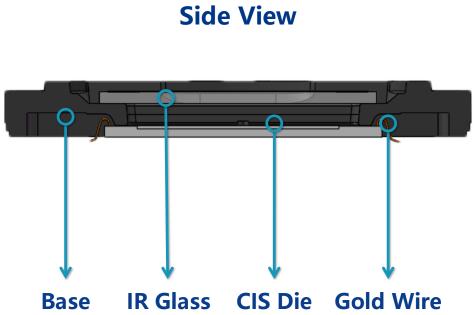
(Soldering COB Technology)

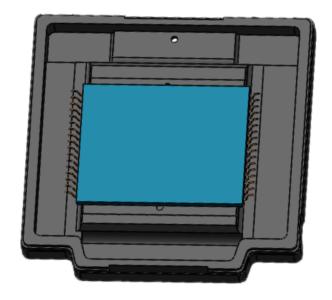
• V4.3 —•

COM Chip







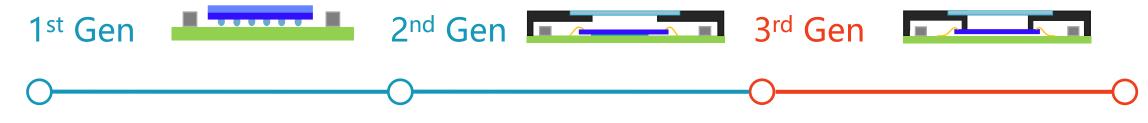


Bottom View





Soldering COB Technology





Poor optical performance

Concern of reliability

Simple manufacturing process

- COR
- Ultrasonic COB
- Better reliability with gold wire bonding
- Improved optical performance with CSP white glasses removed
- High-cost and complex manufacturing process
- Moving particle issue

COM

Soldering COB

- Less moving particle
- Reduced optical tilt error
- Superior reliability of bonding
- Better heat dissipation
- More cost-effective manufacturing
- Need IR glass with mask





COM Roadmap

Series	CIS Model	COM Packaging Size	Status
13M	GC13053	8.5*8.5	Ready
8M	GC08A3	6.5*6.5 / 8.5*8.5	Ready
5M	GC5035	6.5*6.5 / 8.5*8.5	Ready
HD	GC1009	5.6*2.8	Ready

- Product roadmap is subject to change without notice
- Please contact GalaxyCore representative for details



